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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 4937.40-2025

**Semiconductor devices - Mechanical and climatic test methods
- Part 40: Board level drop test method using a strain gauge**

半导体器件 机械和气候试验方法 第40部分：采用应变仪的板级跌落试验方法

(English Translation)

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Foreword

This document complies with the provisions of GB/T 1.1-2020 "Standardization Work Guidelines Part 1: Structure and Drafting Rules of Standardization Documents".

Drafting.

This document is Part 40 of GB/T 4937, "Mechanical and Climatic Test Methods for Semiconductor Devices". GB/T 4937 has been published.

The following section.

---Part 1: General Provisions;

---Part 2: Low Pressure;

---Part 3: External Visual Inspection;

---Part 4: Highly Accelerated Steady-State Damp Heat Test (HAST);

---Part 8: Sealing;

---Part 10: Mechanical Impact Devices and Components;

---Part 11: Rapid Temperature Change in Two-Liquid Tank Method;

---Part 12: Sweep Frequency Vibration;

---Part 13: Salt Spray;

---Part 14: Lead Strength (Lead Wire Secureness);

---Part 15: Solder Heat Resistance of Through-Hole Mounting Devices;

---Part 16: Particle Collision Noise Detection (PIND);

---Part 17: Neutron Irradiation;

---Part 18: Ionizing Radiation (Total Dose);

---Part 19: Chip Shear Strength;

---Part 20: Combined effects of moisture and soldering heat on molded surface mount devices;

---Part 20-1. Handling, Packaging, Marking, and Shipping of Surface Mount Devices Sensitive to the Combined Effects of Moisture and Solder Heat;

- Part 21: Solderability;
- Part 22: Bond Strength;
- Part 23: High-Temperature Operating Life;
- Part 24: Accelerated Moisture Resistance Test with Unbiased Strong Accelerated Stress;
- Part 25: Temperature Cycling;
- Part 26: Electrostatic Discharge (ESD) Sensitivity Testing Human Model (HBM);
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- Part 36: Steady-state acceleration;
- Part 37: Plate Drop Test Method Using Accelerometers;
- Part 38: Soft Fault Testing Methods for Semiconductor Devices with Storage;
- Part 39: Measurement of moisture diffusivity and water solubility of organic materials for semiconductor devices;
- Part 40: Plate Drop Test Method Using Strain Gauges;
- Part 42: Temperature and Humidity Storage;
- Part 44: Test methods for single-event effects (SEE) by neutron irradiation on semiconductor devices.

This document is equivalent to IEC 60749-40:2011 "Mechanical and climatic testing methods for semiconductor devices - Part 40: Strain-based testing".

The plate drop test method for the instrument.

The following minimal editorial changes have been made to this document.

- Added a note to the "Explanation" chapter;
- Added a note to A.3.4.4.

Please note that some content in this document may involve patents. The issuing organization of this document assumes no responsibility for identifying patents.

This document was proposed by the Ministry of Industry and Information Technology of the People's Republic of China.

This document is under the jurisdiction of the National Semiconductor Device Standardization Technical Committee (SAC/TC78).

Introduction

Semiconductor devices are general-purpose basic products in the electronics industry chain and are the most basic units in electronic systems. GB/T 4937 "Semiconductor Devices" the "Mechanical and Climate Test Methods for Semiconductor Devices" is a fundamental and universal standard for testing semiconductor devices, used for evaluating and assessing semiconductors.

The device plays a crucial role in quality and reliability and is planned to consist of 44 parts.

---Part 1: General Principles. The purpose is to establish general guidelines for mechanical and climatic testing methods for semiconductor devices.

---Part 2: Low Pressure. The purpose is to test the ability of components and materials to avoid electrical breakdown failure.

---Part 3: External Visual Inspection. The purpose is to inspect whether the materials, design, structure, markings, and manufacturing processes of semiconductor devices meet the required standards.

Requirements for procurement documents.

---Part 4: Strong Accelerated Steady-State Damp Heat Test (HAST). The purpose is to specify the Strong Accelerated Steady-State Damp Heat Test (HAST) to detect...

To test the reliability of non-hermetically sealed semiconductor devices in humid environments.

---Part 5: Steady-State Temperature and Humidity Offset Lifetime Test. The purpose is to specify the steady-state temperature and humidity offset lifetime test to detect non-hermetic properties.

Reliability of packaged semiconductor devices in humid environments.

---Part 6: High-Temperature Storage. The purpose is to investigate the effects of high-temperature storage on semiconductor devices without applying electrical stress.

---Part 7: Internal Moisture Measurement and Other Residual Gas Analysis. The purpose is to assess the quality of the packaging process and provide information on the gas content.